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Semiconductor radiation detecting component for e.g. radiation image measuring device used in medical radiation - has several solder bumps formed on portions of electrodes on one surface side of semiconductor crystal on which no organic films are formed

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Number of Countries: 001 Number of Patents: 001

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Main IPC	Week
JP 9083007	A	19970328	JP 95234142	A	19950912	H01L-031/09	199723 B

Priority Applications (No Type Date): JP 95234142 A 19950912

Patent Details:

Patent	Kind	Lan	Pg	Filing	Notes	Application	Patent
JP 9083007	A		4				

Abstract (Basic): JP 9083007 A

The component has a semiconductor crystal (7) with several electrodes (5) on one surface side and one whole electrode (6) on the other surface side.

On the surface side with several electrodes, organic insulating films (1) are formed on portions of the electrodes. Several solder bumps (93) are formed on portions of the electrodes on which no organic films are formed.

USE/ADVANTAGE - For e.g. non-destructive test radiation. Efficiently protects semiconductor surface due to formed strong solder bumps. Prevents e.g. pixel chip, deterioration of solder bump characteristics, solder bump deficit.

Dwg.1/4

Title Terms: SEMICONDUCTOR; RADIATE; DETECT; COMPONENT; RADIATE; IMAGE; MEASURE; DEVICE; MEDICAL; RADIATE; SOLDER; BUMP; FORMING; PORTION; ELECTRODE; ONE; SURFACE; SIDE; SEMICONDUCTOR; CRYSTAL; NO; ORGANIC; FILM; FORMING

Derwent Class: S03; S05; U11; U12

International Patent Class (Main): H01L-031/09

International Patent Class (Additional): G01T-001/24; H01L-027/14

File Segment: EPI

Manual Codes (EPI/S-X): S03-G02B2G; S05-D02; U11-C05G2B; U12-A03